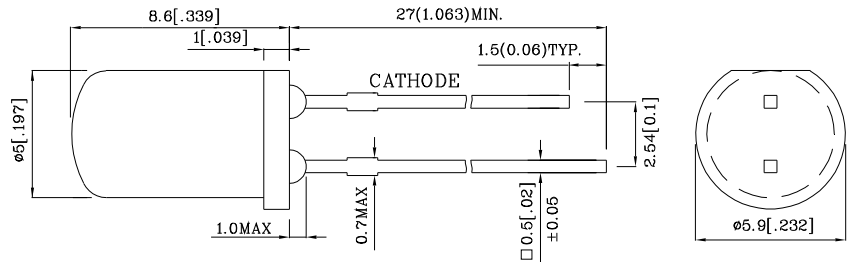


Features

- OUTSTANDING MATERIAL EFFICIENCY.
- RELIABLE AND RUGGED.
- I.C. COMPATIBLE.
- RoHS COMPLIANT.



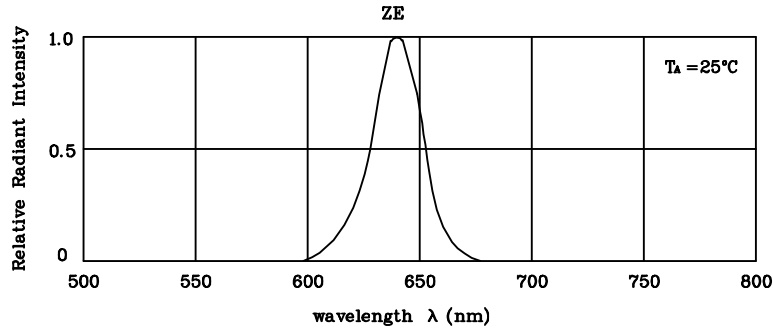
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

Absolute maximum ratings (TA=25°C)		ZE (InGaAlP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	30	mA
Forward Current (peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	150	mA
Power Dissipation	PT	120	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm below package base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm below package base]	260°C For 5 Seconds		

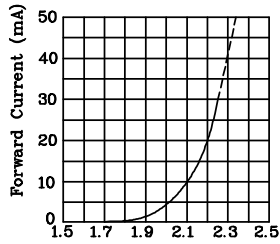
Operating Characteristics (TA=25°C)		ZE (InGaAlP)	Unit
Forward Voltage (typ.) (IF=20mA)	VF typ	2.2	V
Forward Voltage (max.) (IF=20mA)	VF max	2.8	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=20mA)	λ peak	640	nm
Wavelength of Dominant Emission (IF=20mA)	λ D	630	nm
Spectral Line Full Width At Half-Maximum (IF=20mA)	Δλ	25	nm
Capacitance (VF=0V, f=1MHz)	C	27	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA) mcd		Wavelength nm λ P	Viewing Angle 2θ 1/2
				min.	typ.		
XLZE104W	Red	InGaAlP	Water Clear	2500	3990	640	45°
Published Date : APR 13,2005		Drawing No : XDSA7657		V1	Checked : B.L.LIU		P.1/3

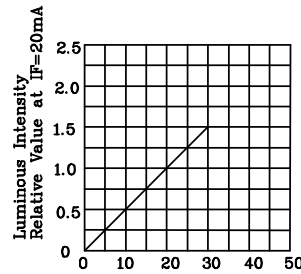


RELATIVE INTENSITY Vs. WAVELENGTH

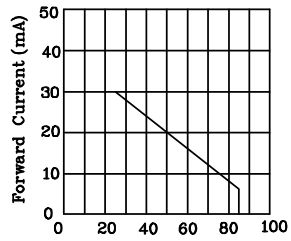
❖ ZE



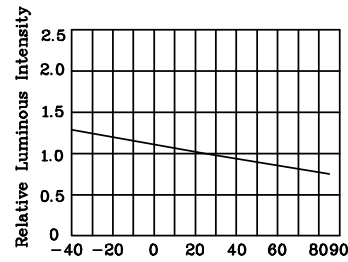
FORWARD CURRENT Vs
FORWARD VOLTAGE



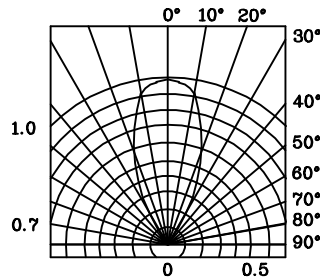
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

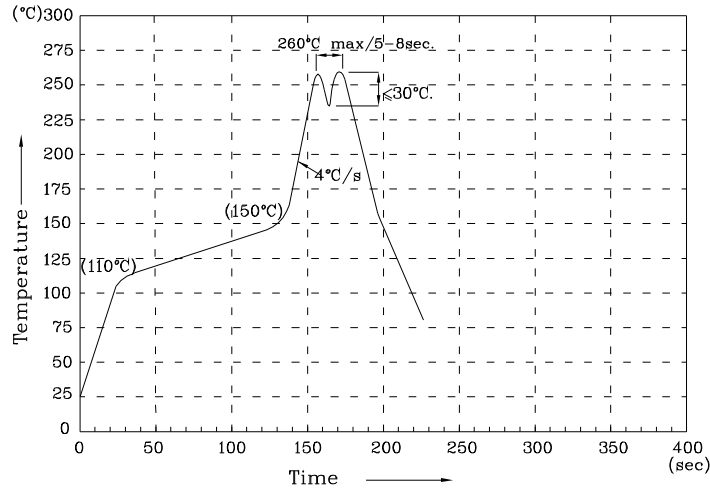
1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



XLZE104W

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.